IPC ASSOCIATION CON ELECTRONICS IND	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mf	g Informati	on	
upplier In	formation								,					
Company name*			Company un	Company unique ID			Unique ID Authority				Response Date*			
nsemi											2025-07-04			
Contact Name		Title - Contact			F	Phone - Contact*				Email - Contact*				
Product-Env-	Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Re	epresentative*	Title - Representative			F	Phone - Representative*			Email - Representative*					
Product-Env-	Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Re	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version Manufacturing Site		V	Veight*	UOM	Unit Type	
	FOD8160 SSO5 3.3		SSO5 3.3V 10MB	SO5 3.3V 10MB		2025-07-04 PBB		3B	1	97.151	mg	Each		
	ring Proccess Information Plating / Grid Array N		Germinal Base	Alloy	STD-020 MSL	Rating	Peak Proce	es Rody Ten	nerature	Max Time at Peak	Temperatu	ure Numb	er of Reflow Cyc	les
		CU Alloy 1		31D-020 MISL	Kanng		Peak Process Body Temperat					er of Kerlow Cyc	les	
omments	tite 1 iii (511) - aimtaitu		Alloy	1			200			130	second	io J		
	num time at peak tempera	ture during sol	Idering is 10-3	M seconds										
	num time at peak tempera rmation regarding materia													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material Weight Unit of Measure Lev		Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Coupling Gel	3.5	mg	Supplier	Dimethyl Siloxane	68083-19-2		3.5	mg
Die	1.131	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.071	mg
			Supplier	Silicon (Si)	7440-21-3		1.06	mg
Die Attach	0.223	mg	Supplier	Silver (Ag)	7440-22-4		0.1784	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0446	mg
Lead Frame	36.392	mg	Supplier	Silver (Ag)	7440-22-4		0.2	mg
			Supplier	Zinc (Zn)	7440-66-6		0.044	mg
			Supplier	Iron (Fe)	7439-89-6		0.837	mg
			Supplier	Copper (Cu)	7440-50-8		35.3	mg
			Supplier	Phosphorus (P)	7723-14-0		0.011	mg
Mold Compound-Black	153.98	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		30.8	mg
			Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		6.16	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		35.4	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		4.62	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		77	mg
Plating	1.69	mg	Supplier	Tin (Sn)	7440-31-5		1.69	mg
Wire Bond - Au	0.235	mg	Supplier	Gold (Au)	7440-57-5		0.235	mg